

I claim:

1. A susceptor for supporting a semiconductor wafer, comprising:

a surface for supporting a semiconductor wafer, said surface having a concave shape; and

a heater thermally coupled to said surface for heating said surface.

2. The susceptor according to claim 1, wherein said surface has a center portion and an outer portion surrounding said center portion, and wherein a distance between said center portion and a plane defined by a circle along said outer portion is greater than 200  $\mu\text{m}$ .

3. The susceptor according to claim 2, wherein said distance is greater than 500  $\mu\text{m}$ .

4. The susceptor according to claim 2, wherein said circle is defined with a diameter of substantially 300 mm.

5. The susceptor according to claim 1, wherein said susceptor is formed of metal.

6. The susceptor according to claim 1, wherein said heater is configured to heat the wafer to a temperature of at least 400°C.

7. The susceptor according to claim 1 configured to carry a silicon wafer with a diameter of at least 300 mm.

8. The susceptor according to claim 1, wherein said surface is formed with a plurality of concentric, projecting rings.

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